



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

- NOTES:
- MATERIAL:
 - HOUSING: HALOGEN FREE PLASTIC, UL94V-0.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - FINISH:
 - CONTACT:
 - 50 μ M MIN NICKEL UNDER PLATING OVER ALL GOLD FLASH ON CONTACT AREA
 - 50 μ M MIN NICKEL UNDER PLATING OVER ALL GOLD 5 μ M MIN ON CONTACT AREA
 - SOLDER:
 - 50 μ M MIN NICKEL UNDER PLATING OVER ALL GOLD FLASH ON SOLDER AREA
 - FITTING NAIL:
 - 50 μ M MIN NICKEL UNDER PLATING OVER ALL 80 μ M MIN. MATT TIN ON SOLDER TAILS
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO SPEC-51202-XXXX-XXX
 - PACKAGE PLS. REFER TO 51202-XXXX-XX-TRP
 - PART NUMBER

CKT	DIM A	DIM B	DIM C	DIM D	DIM E
004	4.50	7.30	9.50	10.30	7.00
006	7.50	10.30	12.50	13.30	10.00
009	12.00	14.80	17.00	17.80	14.50

QUALITY SYMBOLS	DRAWN BY	DATE	TITLE	
MAJOR	TIANYINGHONG	20/11/03	1.5mm WTB Wafer Conn. SMT R/A Type	
CRITICAL	CHECKED BY	DATE		
GENERAL TOLERANCES (UNLESS SPECIFIED)	XUZHUYONG	20/11/03	SIZE	RFO NO.
X. ±0.5	APPROVED BY	DATE	A4	N/A
.X ±0.25	XUZHUYONG	20/11/03	UNITS	SCALE
.XX ±0.15			mm	1:1
.XXX ±0.1			SCALE	SHEET NO.
ANGLES ±2°			1:1	1 OF 1
			REV	DWG NO.
			C	